IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type ³ Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				ials and Mfg Information					
Supplier	r Information														
Company	name*	Company unique ID				Unique ID Authority					Response Date*				
onsemi												2025-08-01			
Contact N	lame	Title - Contact				Phone - Contact*					Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*		Title - Representative				Phone - Representative*				Email - Representative*				
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item N		Number Mfr Item Name				Effective Da	ite Ve	rsion	Manufacturing Site		V	Veight*	UOM	Unit Type
		FQU13N	10LTU	QF 100V 180mOhm L IPAK			2025-08-01					3	83.557	mg	Each
Manufa	cturing Proccess Informat	ion													
	Terminal Plating / Grid Array Material Te		'erminal Base Alloy J-STD-020		-STD-020 MSL	Rating	Peak Process Body Temper		ody Temperatu	ture Max Time at Peak Te		Temperatu	re Numl	ber of Reflow Cyc	eles
	Matte Tin (Sn) - annealed		CU Alloy NA		NA		0		C	30		second	ls 3		
Comments	3									·					
						·			<u> </u>		·				·
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Priective 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its keloardin shall encompass all such components. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall apply that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.93	mg	Supplier	Silicon (Si)	7440-21-3		5.93	mg
Die Attach	2.35		Supplier	Silver (Ag)	7440-22-4		0.0352	mg
			A	Lead (Pb)	7439-92-1	7a	2.1972	mg
			Supplier	Tin (Sn)	7440-31-5		0.1175	mg
Lead Frame	235.307		В	Nickel (Ni)	7440-02-0		0.001	mg
			Supplier	Iron (Fe)	7439-89-6		0.235	mg
			Supplier	Copper (Cu)	7440-50-8		234.9999	mg
			Supplier	Phosphorus (P)	7723-14-0		0.071	mg
Mold Compound-Black	129.0			Epoxy resin	proprietary data		7.74	mg
			Supplier	Phenolic Resin	Proprietary Data		7.74	mg
			Supplier	Carbon Black (C)	1333-86-4		0.645	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		109.65	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3.225	mg
Plating	8.53	mg	Supplier	Tin (Sn)	7440-31-5		8.53	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg